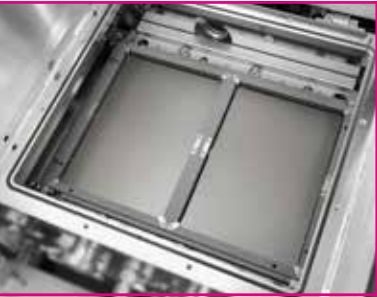


Vacuum soldering systems VADU 200XL and VADU 200XL-W

Soldering of substrates and wafers in series production



View into the process chamber of VADU 200XL.



View into the process chamber of VADU 200XL-W.

The soldering systems of type VADU 200XL are equipped with two separate process chambers and can be operated with paste as well as preforms.

The VADU 200XL-W enables the soldering of wafers up to 12 inch. Customized carriers are also offered by PiNK.

Both soldering systems allow the precise control of all relevant process parameters e.g. the temperature gradients during heating and cooling. Due to its intelligent temperature management the system provides short cycle times and an excellent temperature stability.

System features

- Void-free solder connections
- Soldering with preforms and/or pastes
- Individual soldering profiles
- Soldering temperatures up to 400 °C
- Controlled temperature gradients
- Short cycle times
- Separate soldering and cooling chamber
- Flux-free soldering with formic acid
- Flux management
- Inert gas atmosphere
- Residual oxygen content < 5 ppm
- Reproducibility of the soldering results
- Traceability
- Permanent process control
- Ethernet interface
- Remote maintenance (VPN)
- Low energy and media consumption
- Internationally patented system

Options

- Handling/Transfer systems
- Integrated MES interfaces (e.g. SECS/GEM)

Technical data

Process area (W x D): 410 x 280 mm (e.g. 4 cards à 5 x 7" or 12" wafer)

Clearance height: max. 100 mm

Dimensions of the system (W x D x H): 1,200 x 1,890 x 1,680 mm

Power supply: 3 x 400 V, 50/60 Hz

Power input: 10 kVA

Weight VADU 200XL: 1,200 kg, Weight VADU 200XL-W: 1,400 kg



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